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FOR IMMEDIATE RELEASE

Press Release

Fully Flux Residue Compatible, Room Temperature Fast Flow, Reworkable Underfill SMT 88UL2

(Albany, NY) 12/20/2021 — YINCAE is excited to announce that we have developed and upgraded SMT 88UL to SMT 88UL2, a fully flux residue compatible, room temperature fast flow and easily reworkable underfill.

The compatibility of underfill and flux residue has long been a traditional issue in the electronic industry. This compatibility issue normally leads to underfill flow issue, underfill voids, underfill delamination and solder extrusion during the double reflow process and automotive application. Typically, it is too costly to clean the flux residue in SMT assembly. SMT 88UL2 is designed to be fully compatible with the flux residues of almost all solder paste from major manufacturers. SMT 88UL2 can fast flow into any gap size (less than 1μ) at room temperature and fast cure at lower temperatures without any flow and void issues eliminating cleaning flux residue. Our SMT 88UL2 can withstand multiple 260°C reflow processes without any delamination, solder extrusion and solder ball issues without cleaning flux residue. It has demonstrated excellent drop and thermal cycling performance.

This material can be used as an underfill for flip chip, chip scale package, ball grid array devices, package on package, and land grid array applications. It is also suitable for bare chip protection in a variety of advanced packages such as memory cards, chip carriers, hybrid circuits and multi-chip modules. It is designed for high production and an environment where process speed and thermal dissipation are key concerns.

For more information on YINCAE's SMT 88UL2, or to learn more about what YINCAE offers, please email us at: info@yincae.com. You can also find more information by visiting our website at: www.yincae.com

Founded in 2005 & headquartered in Albany, New York, YINCAE Advanced Materials is a leading manufacturer and supplier of thermal interface materials, underfill solutions, die attach adhesives, electronic materials, & high-performance coatings used in microchip & optoelectronic devices. YINCAE products provide new technologies to support manufacturing processes from wafer level, to package level, to board level and final devices while facilitating smarter and faster production and supporting green initiatives.

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